

AMENDMENTS TO THE CLAIMS

In accordance with 37 C.F.R. §1.121(c), please amend the claims as indicated in marked-up form below, where additions are underlined, deletions are struck through, and new claims are presented without markings.

1-26. (Canceled in a previous paper)

27. (Previously Presented) A method of manufacturing a semiconductor component, the method comprising:

providing a leadframe having a surface, the surface defining a horizontal direction and a line perpendicular to the surface defining a vertical direction;

attaching a semiconductor chip to the leadframe;

providing an integrated passive component comprising a surface layer and an interior layer and further comprising a passive device in the interior layer;

attaching the integrated passive component to the semiconductor chip such that:

the semiconductor chip is located between the integrated passive component and the leadframe; and

the semiconductor chip, the integrated passive component, and the leadframe have a vertical relationship with respect to each other; and

disposing a mold compound around the semiconductor chip, the integrated passive component, and the leadframe such that a portion of the leadframe is exposed outside of the mold compound.

28. (Previously Presented) The method of claim 27 wherein:

providing the leadframe comprises:

providing a quad flat non-leaded leadframe.

29. (Original) The method of claim 27 wherein:

attaching the semiconductor chip to the leadframe comprises:

electrically coupling the semiconductor chip to the leadframe using flip chip interconnects.

30. (Original) The method of claim 27 further comprising:

electrically coupling the integrated passive component to at least one of the semiconductor chip and the leadframe.

31. (Original) The method of claim 27 further comprising:

providing an adhesive layer between the integrated passive component and the semiconductor chip; and

securing the integrated passive component to the semiconductor chip using the adhesive layer.

32. (Previously Presented) The method of claim 27 wherein:

providing the integrated passive component comprises providing a component other than a semiconductor device.

33. (Previously Presented) The method of claim 30 wherein:

electrically coupling the integrated passive component comprises wire bonding the integrated passive component to at least one of the semiconductor chip and the leadframe.

34. (Previously Presented) A method of manufacturing a semiconductor component, the method comprising:

providing a leadframe having a surface, the surface defining a horizontal direction and a line perpendicular to the surface defining a vertical direction;

attaching a semiconductor chip having a first surface area to the leadframe;

attaching an integrated passive component having a second surface area to the semiconductor chip such that:

the semiconductor chip is located between the integrated passive component and the leadframe; and

the semiconductor chip, the integrated passive component, and the leadframe have a vertical relationship with respect to each other; and

disposing a mold compound around the semiconductor chip, the integrated passive component, and the leadframe such that a portion of the leadframe is exposed outside of the mold compound,

wherein:

the second surface area is at least as large as the first surface area; and

the integrated passive component comprises a passive device.

35. (Previously Presented) The method of claim 34 wherein:

providing the leadframe comprises:

providing a quad flat non-leaded leadframe.

36. (Previously Presented) The method of claim 34 wherein:

attaching the semiconductor chip to the leadframe comprises:

electrically coupling the semiconductor chip to the leadframe using flip chip interconnects.

37. (Previously Presented) The method of claim 34 further comprising:

electrically coupling the integrated passive component to at least one of the semiconductor chip and the leadframe.

38. (Previously Presented) The method of claim 37 wherein:

electrically coupling the integrated passive component comprises wire bonding the integrated passive component to at least one of the semiconductor chip and the leadframe.

39. (Previously Presented) The method of claim 34 further comprising:

providing an adhesive layer between the integrated passive component and the semiconductor chip; and

securing the integrated passive component to the semiconductor chip using the adhesive layer.

40. (Previously Presented) The method of claim 34 wherein:

providing the integrated passive component comprises providing a component other than a semiconductor device.

41. (Previously Presented) The method of claim 34 wherein:

the second surface area is larger than the first surface area.

42-46. (Canceled)